

General Description

The MY3415 is the P-Channel logic enhancement mode power field effect transistor is produced using high cell density advanced trench technology.. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, and low in-line power loss are needed in a very small outline surface mount package.

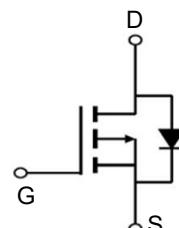
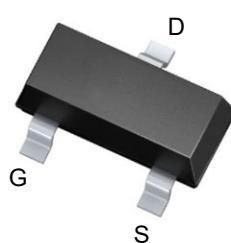
Application

- Power Management
- Portable Equipment
- DC/DC Converter



Features

V _{DSS}	-20	V
I _D	-5	A
R _{DS(ON)} (at V _{GS} = -4.5V)	28	mΩ
R _{DS(ON)} (at V _{GS} = -2.5V)	36	mΩ



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY3415	SOT-23	3415	3000

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Typical	Unit
V _{DSS}	Drain-Source Voltage	-20	V
V _{GSS}	Gate-Source Voltage	±8	V
I _D	Continuous Drain Current (T _C =25°C)	-5	A
	Continuous Drain Current (T _C =70°C)		
I _{DM}	Pulsed Drain Current	-20	A
P _D	Power Dissipation	T _A =25°C	W
		T _A =70°C	
T _J	Operation Junction Temperature	150	°C
T _{STG}	Storage Temperature Range	-55~+150	°C
R _{θJA}	Thermal Resistance Junction to Ambient	120	°C/W

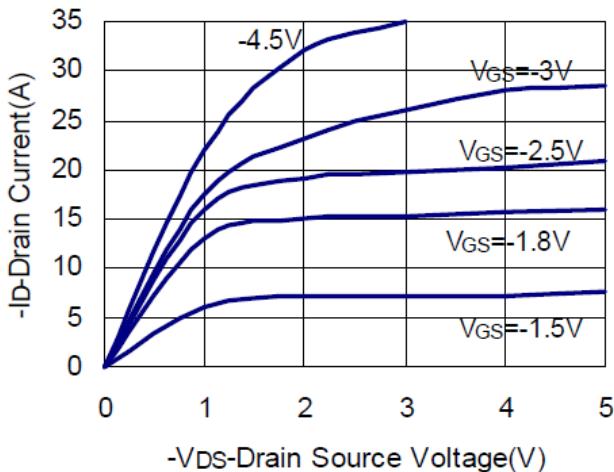
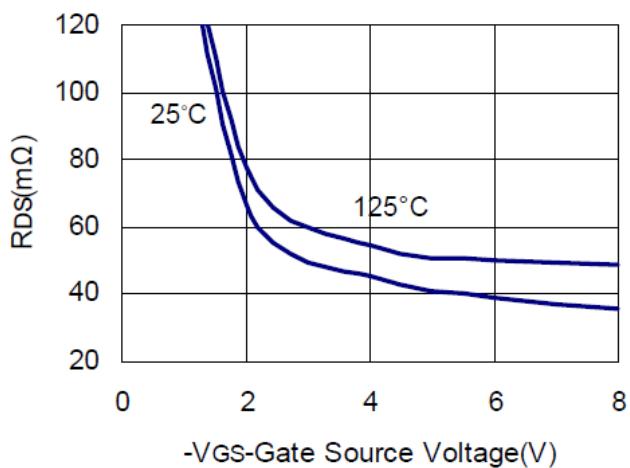
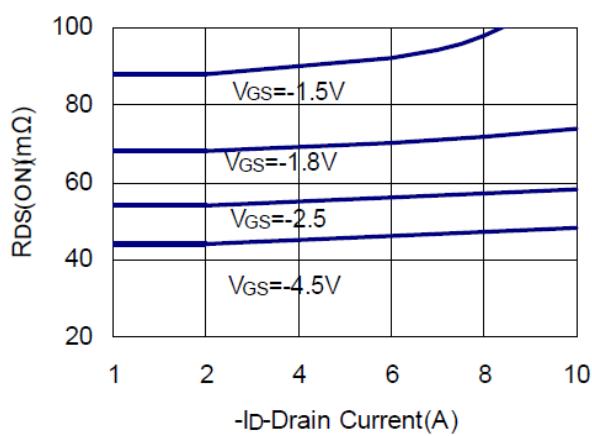
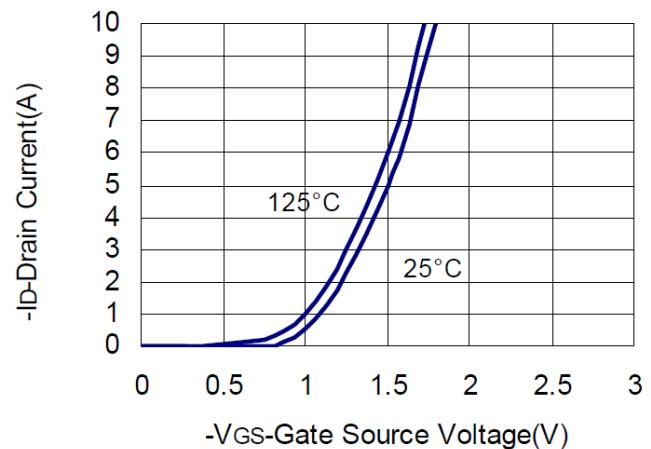
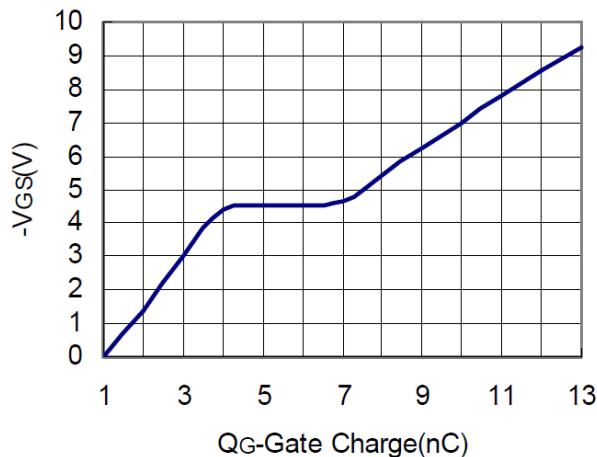
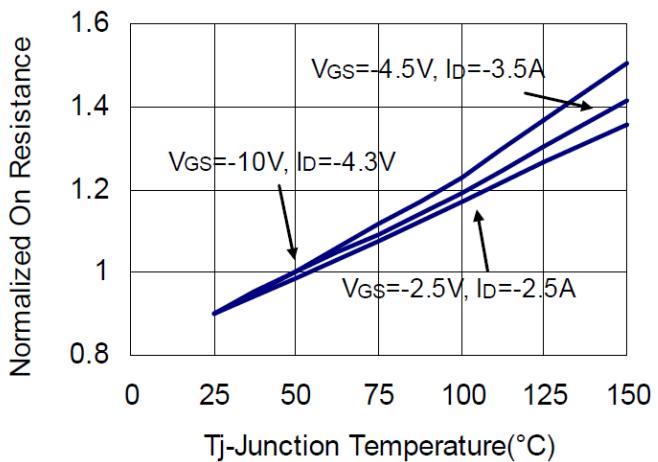
Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

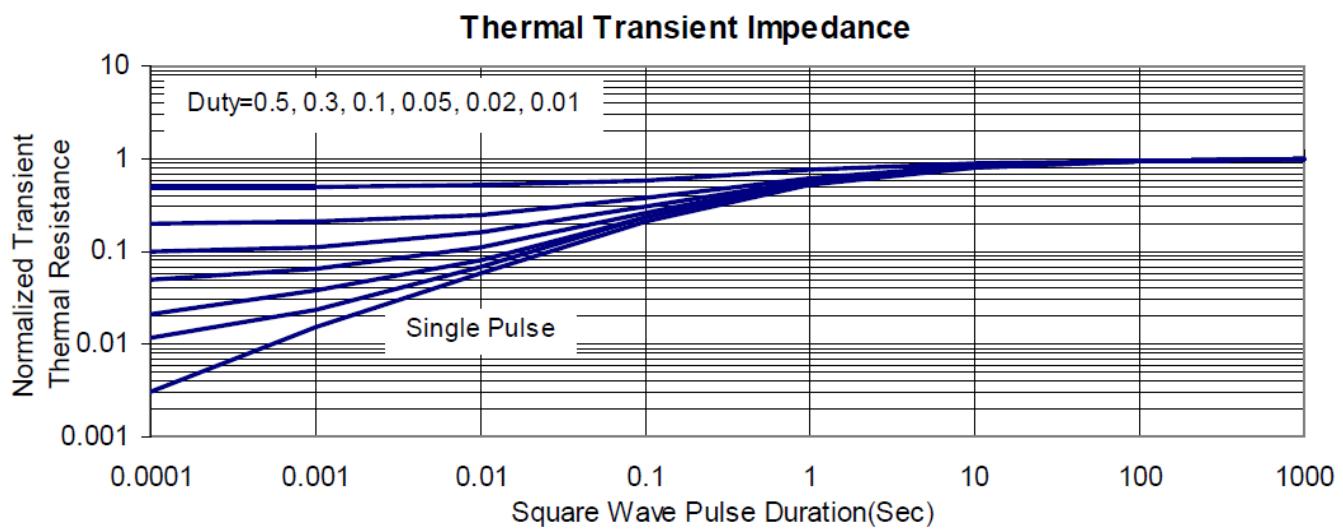
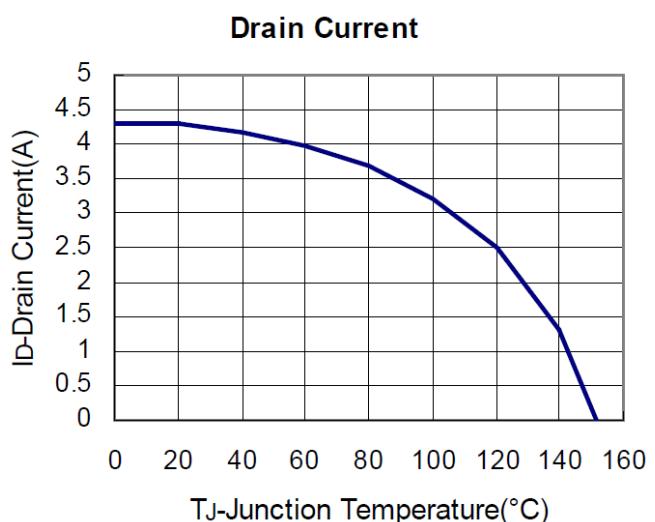
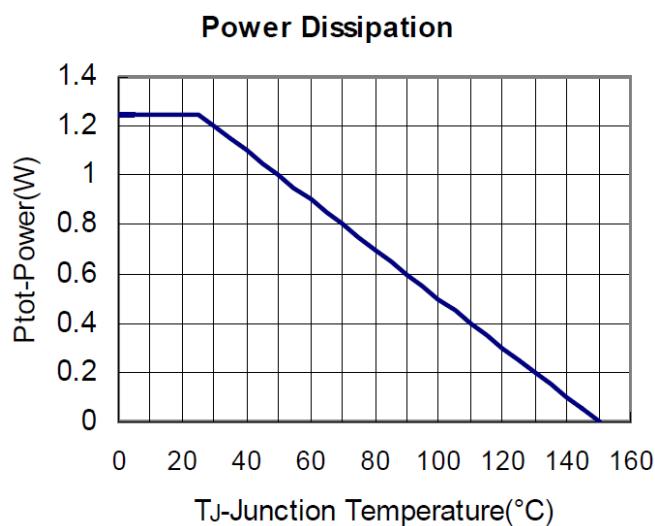
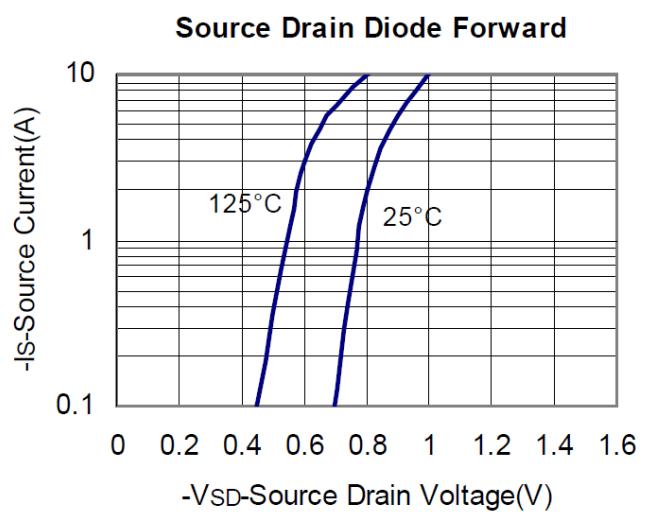
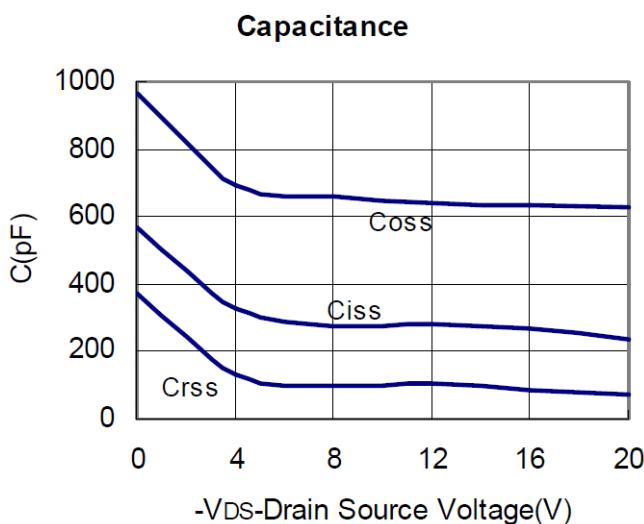
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
Static Parameters							
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-20			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-0.3		-1.0	V	
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 8\text{V}$			± 10	μA	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-12\text{V}$, $V_{GS}=0$			-1	μA	
		$V_{DS}=-12\text{V}$, $V_{GS}=0$ $T_J=55^\circ\text{C}$			-5		
$R_{DS(\text{ON})}$	Drain-Source On-Resistance	$V_{GS}=-4.5\text{V}$, $I_D=-4.3\text{A}$		28	38	$\text{m}\Omega$	
		$V_{GS}=-2.5\text{V}$, $I_D=-3.0\text{A}$		36	45		
		$V_{GS}=-1.8\text{V}$, $I_D=-2.0\text{A}$		56	75		
		$V_{GS}=-1.5\text{V}$, $I_D=-1.0\text{A}$		85	110		
G_{fs}	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-4.0\text{A}$		22		S	
Source-Drain Diode							
V_{SD}	Diode Forward Voltage	$I_S=-1.0\text{A}$, $V_{GS}=0\text{V}$		-0.67	-1.2	V	
Dynamic Parameters							
Q_g	Total Gate Charge	$V_{DS}=-10\text{V}$ $V_{GS}=-4.5\text{V}$ $I_D=-4.0\text{A}$		11.1		nC	
Q_{gs}	Gate-Source Charge			3.1			
Q_{gd}	Gate-Drain Charge			2.4			
C_{iss}	Input Capacitance	$V_{DS}=-10\text{V}$ $V_{GS}=0\text{V}$ $f=1\text{MHz}$		989		pF	
C_{oss}	Output Capacitance			167			
C_{rss}	Reverse Transfer Capacitance			75.5			
$T_{d(on)}$	Turn-On Time	$V_{DS}=-10\text{V}$ $I_D=-3.7\text{A}$ $V_{GEN}=-4.5\text{V}$ $R_G=1\Omega$		712		nS	
T_r				1386			
$T_{d(off)}$	Turn-Off Time			9.1			
T_f				4			

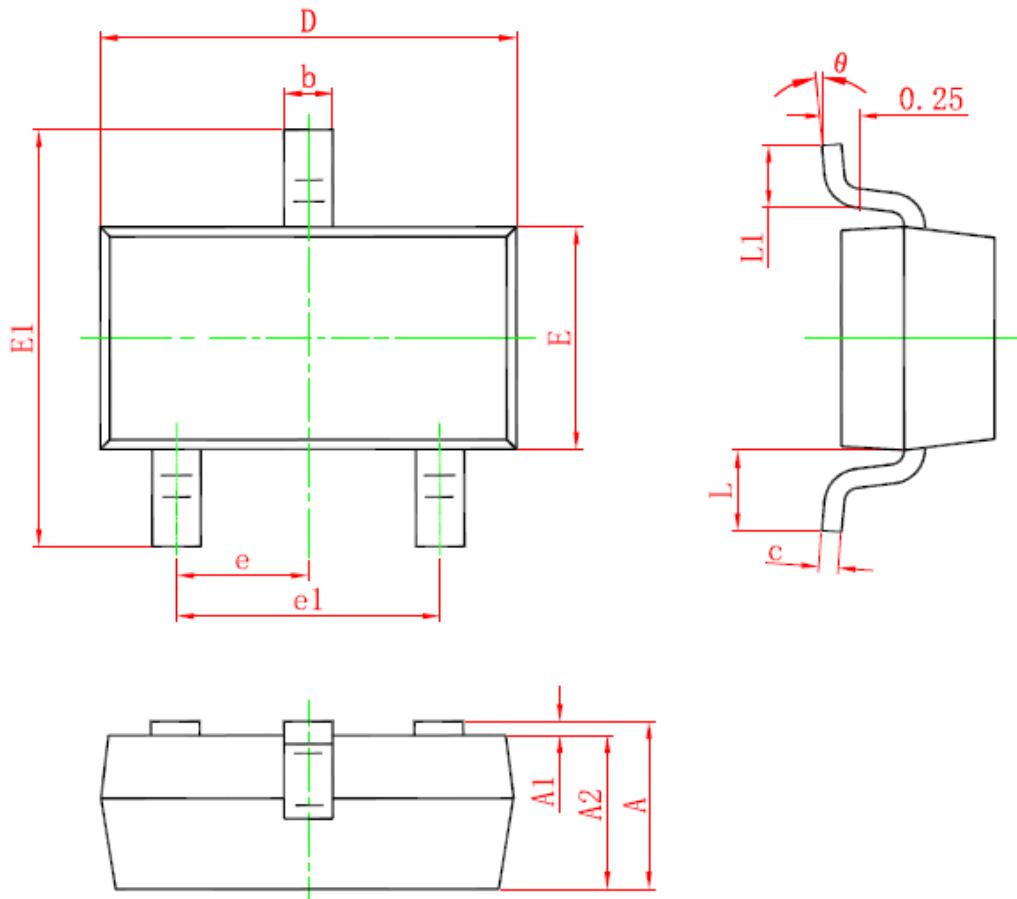
Note: 1. Pulse test: pulse width<=300 μs , duty cycle<=2%

2. Static parameters are based on package level with recommended wire bonding

Switching Time Test Circuit and Waveforms

Output Characteristics

Drain-Source On Resistance

Drain Source On Resistance

Transfer Characteristics

Gate Charge

Drain Source Resistance




Package Mechanical Data-SOT-23


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°